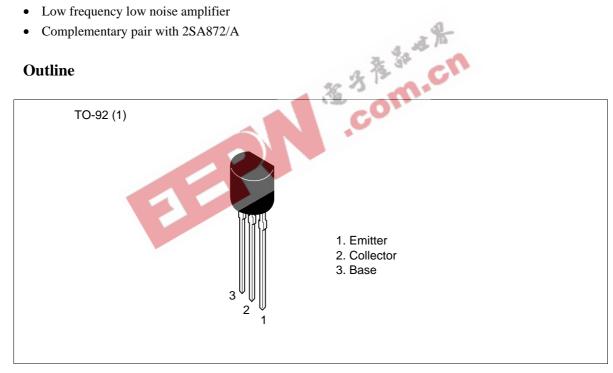
Silicon NPN Epitaxial

HITACHI

Application

- Low frequency low noise amplifier
- Complementary pair with 2SA872/A

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

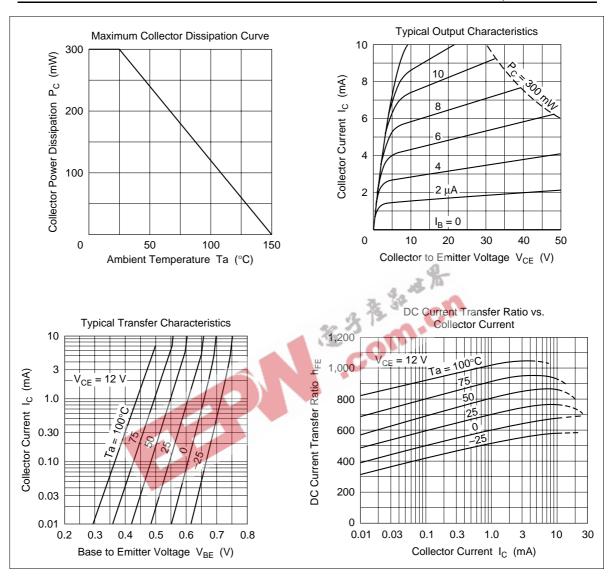
Item	Symbol	2SC1775	2SC1775A	Unit
Collector to base voltage	$V_{\scriptscriptstyle \sf CBO}$	90	120	V
Collector to emitter voltage	V_{CEO}	90	120	V
Emitter to base voltage	V_{EBO}	5	5	V
Collector current	I _c	50	50	mA
Collector power dissipation	P _c	300	300	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-50 to +150	°C

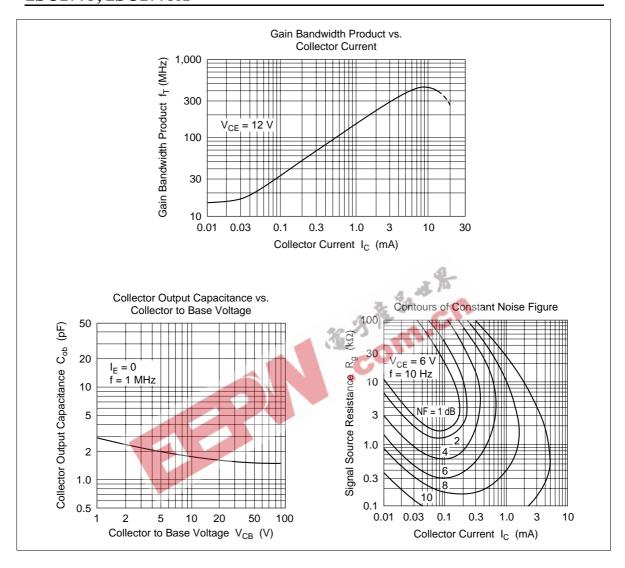
Electrical Characteristics (Ta = 25°C)

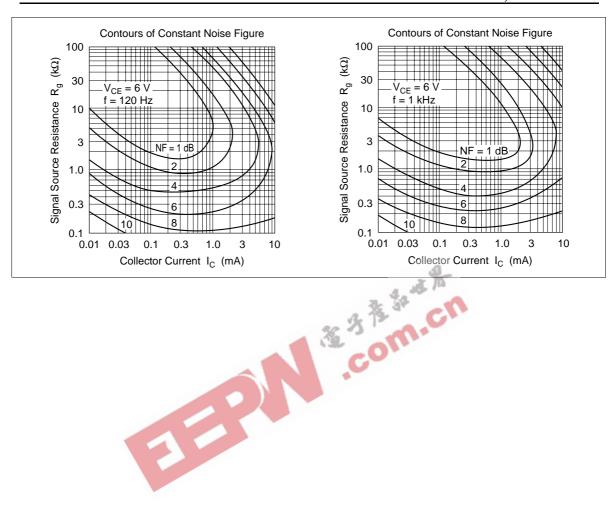
Electrical Characteristics (Ta = 25°C)				25017750						
		2SC1	775		2SC17	775A	12.	n.		
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test condition	าร
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	90			120	; 0 1		V	$I_C = 1 \text{ mA}, R_{BE}$	= ∞
Collector cutoff current	I _{CBO}		=	0.5	_		_	μΑ	$V_{CB} = 75 \text{ V}, I_{E} =$	= 0
		7	71	-	_	_	0.5	μΑ	$V_{CB} = 100 \text{ V}, I_{E}$	= 0
DC current transfer ratio	h _{FE1} *1	400	_	1200	400	_	1200		V _{CE} = 12 V, I _C =	= 2 mA
	h _{FE2}	160	_	_	160	_	_		$V_{CE} = 12 \text{ V},$ $I_{C} = 0.1 \text{ mA}$	
Base to emitter voltage	V _{BE}	_	_	0.75	_	_	0.75	V	V _{CE} = 12 V, I _C =	= 2 mA
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.5	_	_	0.5	V	$I_C = 10 \text{ mA}, I_B =$	= 1 mA
Gain bandwidth product	f _T	_	200	_	_	200	_	MHz	V _{CE} = 12 V, I _C =	= 2 mA
Collector output capacitance	Cob	_	1.6	_	_	1.6	_	pF	$V_{CB} = 25 \text{ V}, I_{E} = f = 1 \text{ MHz}$	= 0,
Noise figure	NF	_	_	5.0	_	_	5.0	dB	$V_{CE} = 6 \text{ V},$ $I_{C} = 50 \mu\text{A},$ $R_{g} = 50 k\Omega$	f = 10 Hz
		_	_	1.5	_	_	1.5	dB	_	f = 1 kHz

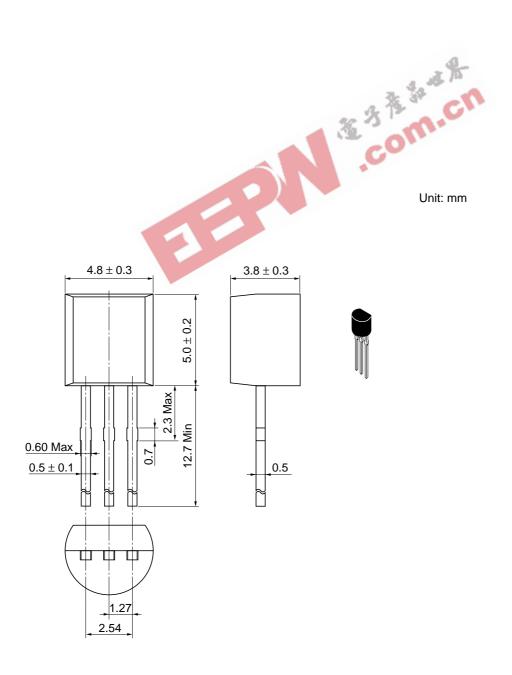
Note: 1. The 2SC1775/A is grouped by h_{FE1} as follows.

E	F
400 to 800	600 to 1200









Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

Cautions

- 1. Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
- 2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
- 3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
- 4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as failsafes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
- 5. This product is not designed to be radiation resistant.
- 6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
- 7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.

Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 URI

NorthAmerica http:semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg Europe

http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi.com.hk/eng/bo/grp3/index.htm

Japan http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group.

Whitebrook Park

Lower Cookham Road

Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <44> (1628) 585000 Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd

Taipei Branch Office 3F, Hung Kuo Building. No.167 Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

Copyright ' Hitachi, Ltd., 1999. All rights reserved. Printed in Japan.